

## PCB Adjustments for Tool Reference

Layers - If greater than typical, consider moving up and right on charts

Microvias – For PCBs thicker than 1.60 mm, 0.062 inches additional evaluation may be required

Cu Wt – If greater than two ounces (70 micron), consider moving up and right on charts

RC – If greater than maximum range, consider moving right on charts

Aspect Ratio – If greater than maximum range, consider moving right on charts

Retained Cu – If greater than maximum, consider moving up and right on charts

PTH Cu ( $\mu\text{m}$ ) – If less than typical, consider moving up and right on charts

Surface Finish – If HASL or Reflowed Solder, consider moving up on chart for each cycle (treat as an additional reflow cycle)

Multiple Lamination Cycles – If multiple lamination cycles, consider moving up on chart for each additional cycle (treat as an additional reflow cycle)

Mixed Materials – If mixed materials, use lowest performing material as reference and consider moving up and right on chart

Blind and Buried Vias – If yes, consider moving up and right on charts

External Planes – If yes, consider moving up and right on charts

**FIGURE 15.** Adjustments based on design features or process conditions.